## DESCRIPTION

These low capacitance diode arrays are multiple, discrete, isolated junctions fabricated by a planar process and mounted in a 14-pin package for use as steering diodes protecting up to eight I/O ports from positive ESD, EFT, or surge by directing them to the positive side of the power supply (pin 14)*. An external TVS diode may be added between the positive supply line and ground to prevent overvoltage on the supply rail. They may also be used in fast switching core-driver applications. This includes computers and peripheral equipment such as magnetic cores, thin-film memories, plated-wire memories, etc., as well as decoding or encoding applications. These arrays offer many advantages of integrated circuits such as high-density packaging and improved reliability. This is a result of fewer pick and place operations, smaller footprint, smaller weight, and elimination of various discrete packages that may not be as user friendly in PC board mounting. They are available with either Tin-Lead plating terminations or as RoHS Compliant with annealed matte-Tin finish by adding an "e3" suffix to the part number.
*See MAD1106(e3) for directing negative transients to ground.
IMPORTANT: For the most current data, consult MICROSEMI's website: http:I/www.microsemi.com


$-1-F \quad-1 \mid-0$


|  | INCHES |  | MILLIMETERS |  |
| :---: | :---: | :---: | :---: | :---: |
| DIM | MIN | MAX | MIN | MAX |
| A | 0.740 | 0.780 | 18.80 | 19.81 |
| B | 0.235 | 0.265 | 5.969 | 6.731 |
| C | 0.120 | 0.140 | 3.048 | 3.556 |
| D | 0.270 | 0.330 | 6.858 | 8.382 |
| E | 0.320 | 0.380 | 8.128 | 9.652 |
| F | 0.100 BSC |  | 2.540 BSC |  |
| G | 0.015 |  | 0.021 | 0.381 |
| H | 0.017 | 0.023 | 0.431 | 0.584 |
| I | 0.140 | 0.160 | 3.556 | 4.064 |

OUTLINE


CIRCUIT CONFIGURATION

